



Click [here](#) for the 3D model.

#### General Information

|                          |                                                                  |
|--------------------------|------------------------------------------------------------------|
| Series                   | ESD SMD Comm COG                                                 |
| Style                    | SMD Chip                                                         |
| Description              | SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I |
| Features                 | Temperature Stable, Low ESR, Class I                             |
| RoHS                     | Yes                                                              |
| Termination              | Flexible Termination                                             |
| Marking                  | No                                                               |
| AEC-Q200                 | No                                                               |
| Typical Component Weight | 14 mg                                                            |
| Shelf Life               | 78 Weeks                                                         |
| MSL                      | 1                                                                |

#### Specifications

|                                                                    |                        |
|--------------------------------------------------------------------|------------------------|
| Capacitance                                                        | 0.047 uF               |
| Measurement Condition                                              | 1 kHz 1.0Vrms          |
| Tolerance                                                          | 1%                     |
| Voltage DC                                                         | 25 VDC                 |
| ESD Level per AEC-Q200                                             | 25,000 V ESD Level     |
| Dielectric Withstanding Voltage                                    | 62.5 VDC               |
| Temperature Range                                                  | -55/+125°C             |
| Temp. Coefficient                                                  | COG                    |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor                                                 | 0.1% 1 kHz 1.0Vrms     |
| Aging Rate                                                         | 0% Loss/Decade Hour    |
| Insulation Resistance                                              | 21.2766 GOhms          |

#### Dimensions

|           |                  |
|-----------|------------------|
| Chip Size | 0805             |
| L         | 2mm +/-0.3mm     |
| W         | 1.25mm +/-0.3mm  |
| T         | 1.25mm +/-0.15mm |
| S         | 0.6mm MIN        |
| B         | 0.5mm +/-0.25mm  |

#### Packaging Specifications

|                    |                          |
|--------------------|--------------------------|
| Packaging          | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 2500                     |

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